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(12) **United States Design Patent**  
**Mecchella et al.**

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(54) **ELECTRONIC DEVICE COVER**  
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(US)

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(\* ) Notice: This patent is subject to a terminal dis-  
claimer.

(\*\*) Term: **14 Years**

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(52) **U.S. Cl.**  
USPC ..... **D14/440**

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G02F 1/1533; G02F 2001/133317; H04M  
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379/426, 433.11, 455; 455/575.1,  
455/575.8, 457.1; 190/100; 206/305, 320,  
206/45.2; D21/469; 312/240  
See application file for complete search history.

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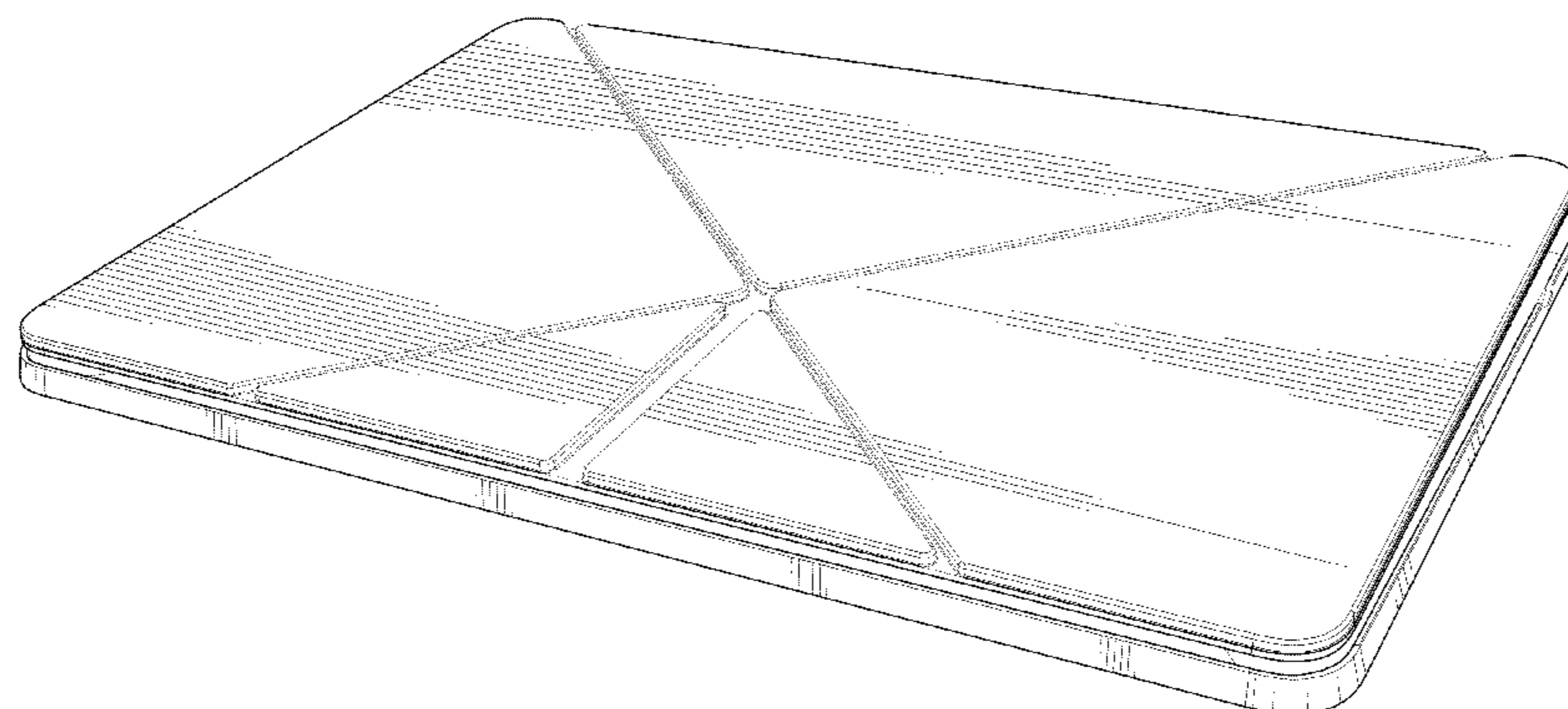
(57) **CLAIM**

The ornamental design for an electronic device cover, as  
shown and described.

**DESCRIPTION**

FIG. 1 is a first perspective view of an electronic device cover  
for holding an electronic device, taken from above;  
FIG. 2 is a second perspective view of the electronic device  
cover of FIG. 1, taken from below;  
FIG. 3 is a top plan view of the electronic device cover of FIG.  
1;  
FIG. 4 is a bottom plan view of the electronic device cover of  
FIG. 1;  
FIG. 5 is a front elevation view of the electronic device cover  
of FIG. 1;  
FIG. 6 is a back elevation view of the electronic device cover  
of FIG. 1;  
FIG. 7 is a right-side elevation view of the electronic device  
cover of FIG. 1; and,  
FIG. 8 is a left-side elevation view of the electronic device  
cover of FIG. 1.  
The broken lines are directed to unclaimed portions and form  
no part of the claimed design.

**1 Claim, 6 Drawing Sheets**



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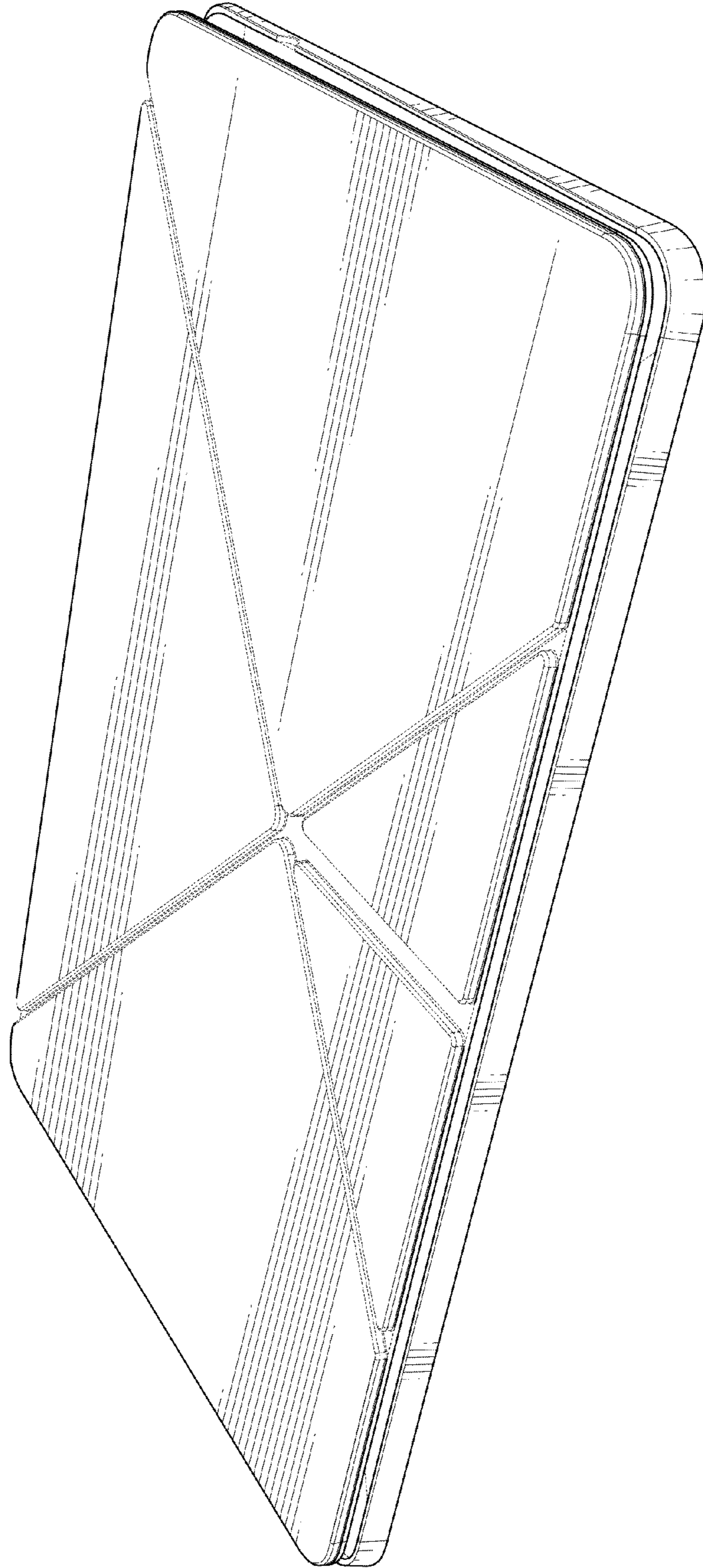


FIG. 1

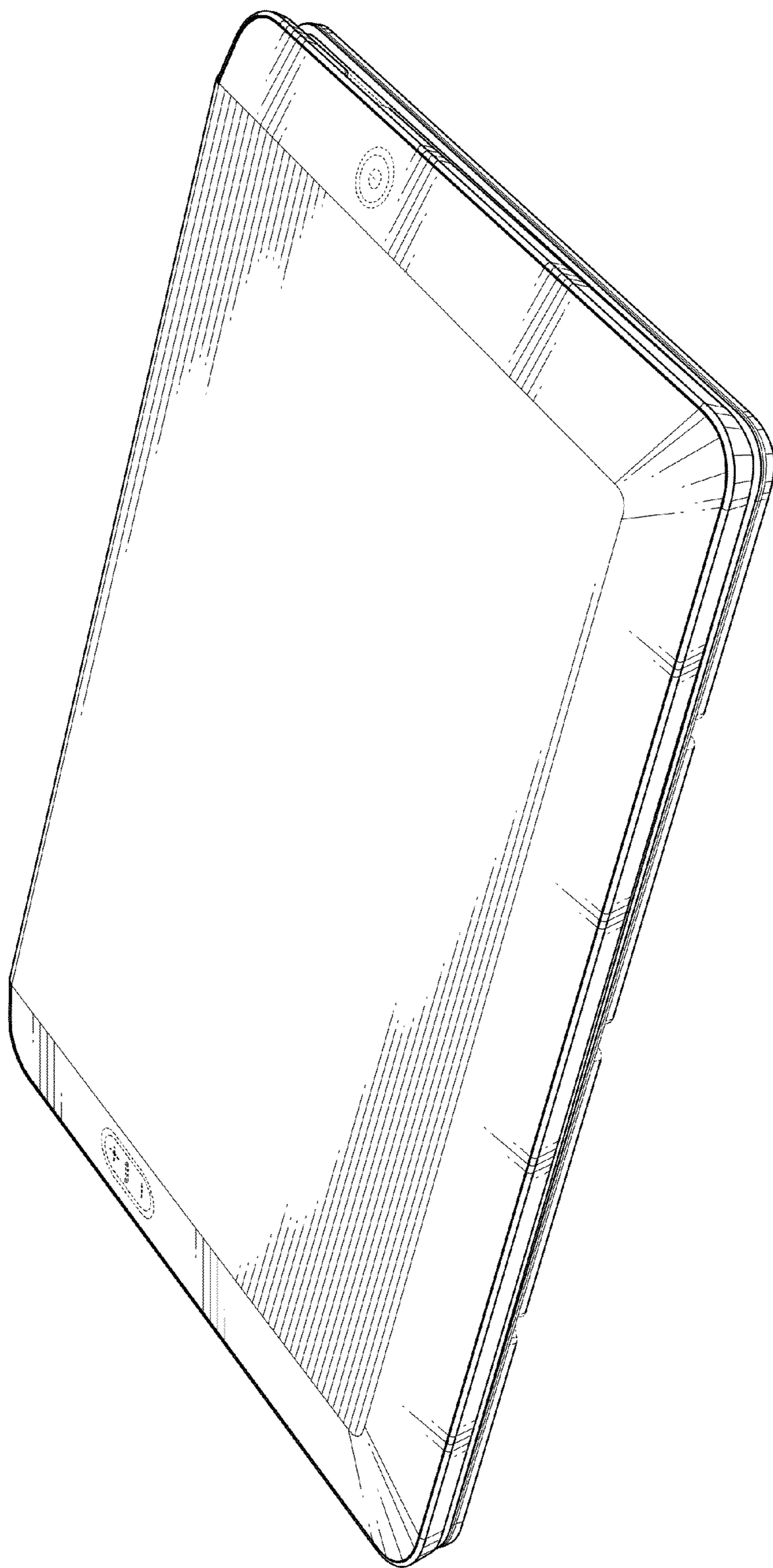


FIG. 2

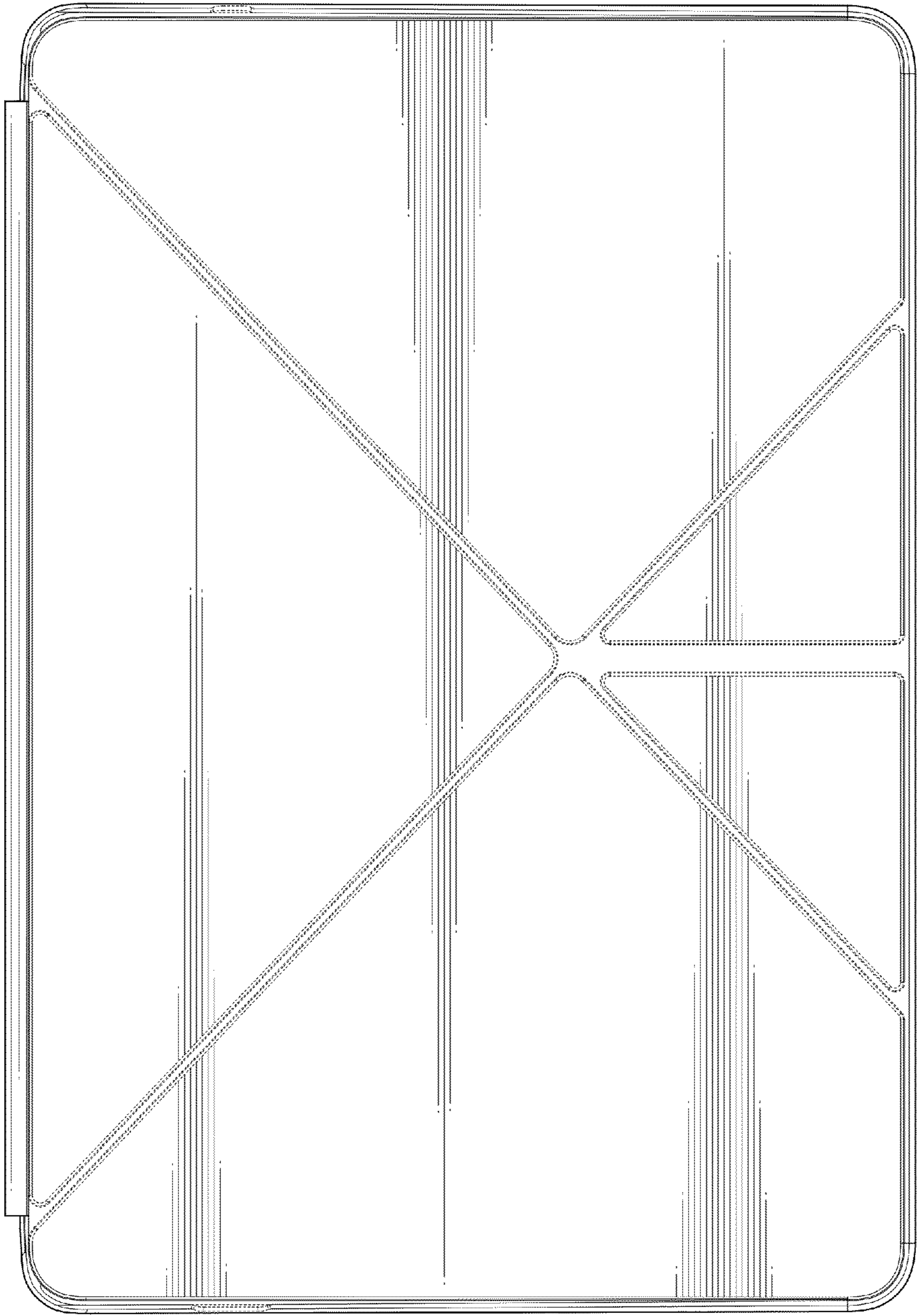


FIG. 3



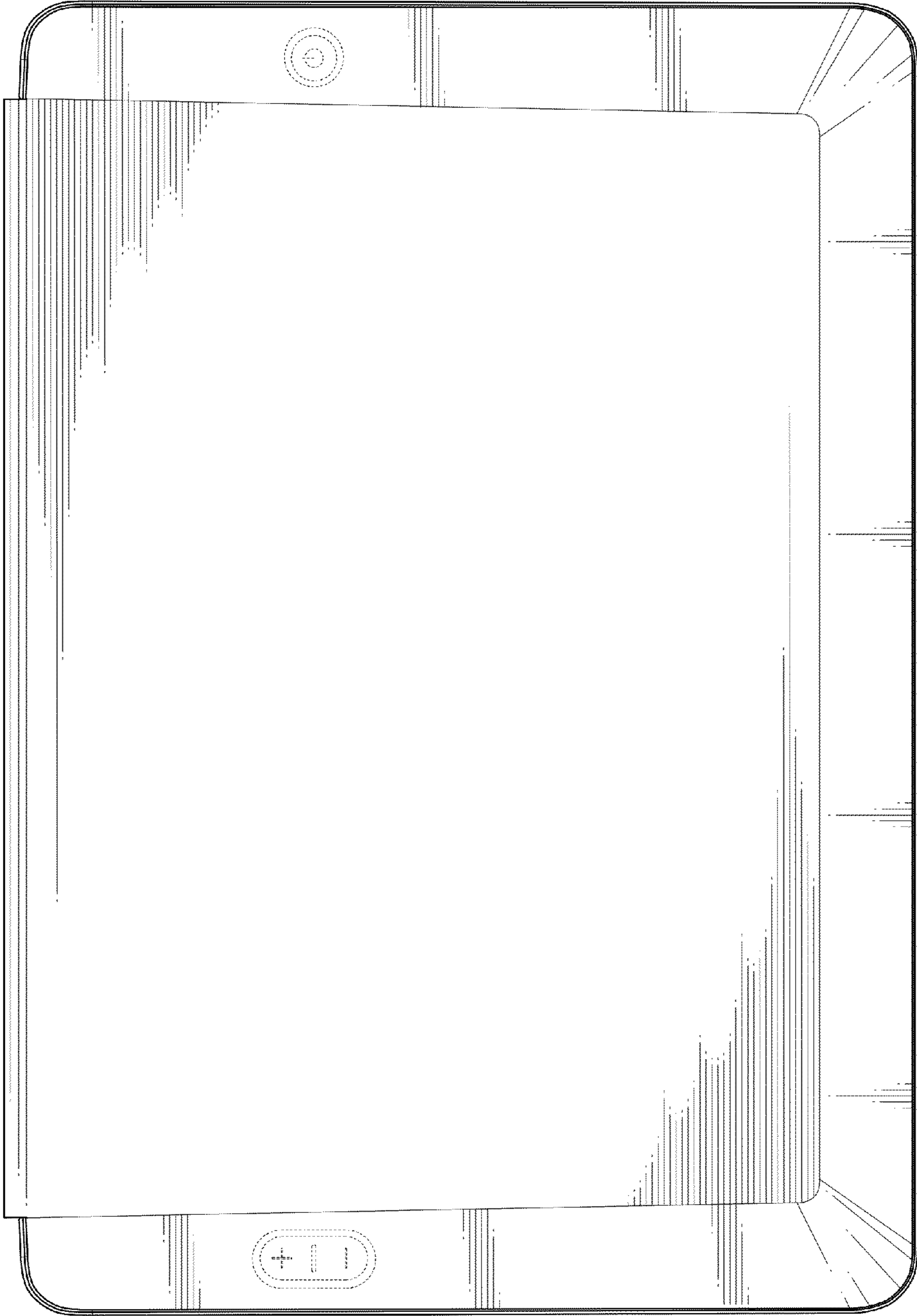


FIG. 4

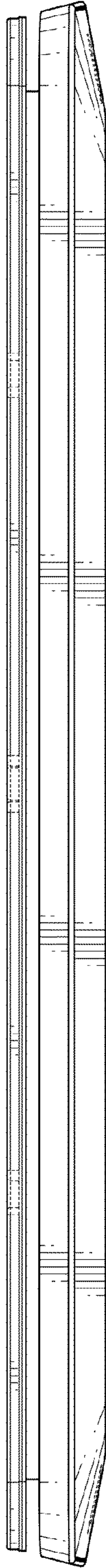


FIG. 5

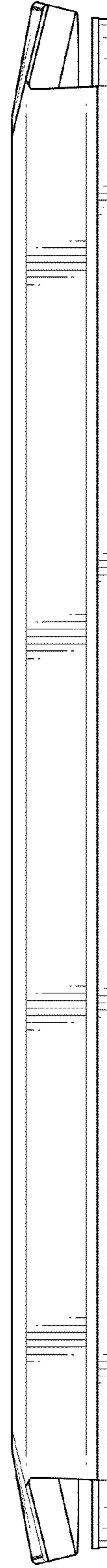


FIG. 6

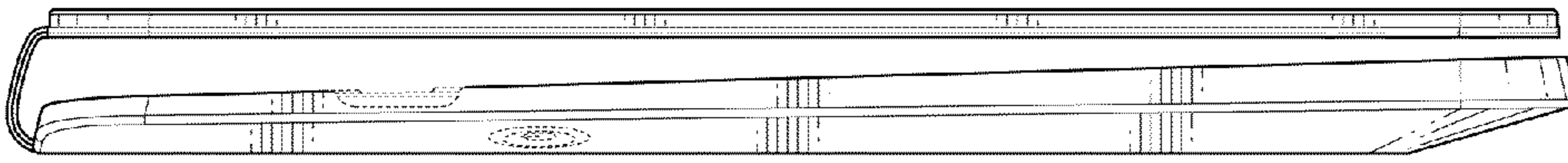


FIG. 8

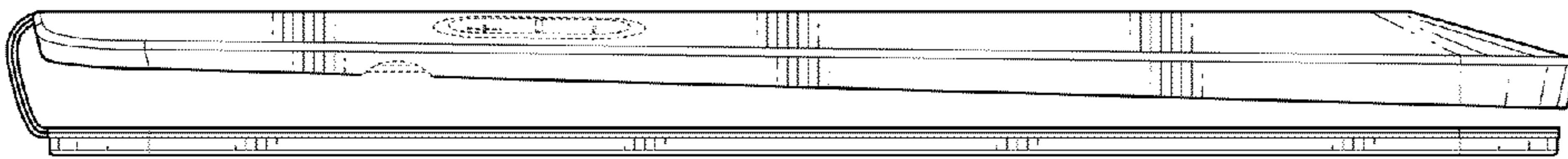


FIG. 7